



DMP4011SPS

P-CHANNEL ENHANCEMENT MODE MOSFET PowerDI5060-8

Product Summary

BV _{DSS}	Rds(on) max	I _{D MAX} T _C = +25°C
-40V	10mΩ @ V _{GS} = -10V	-76A
	14mΩ @ V _{GS} = -4.5V	-58A

Description and Applications

This new generation MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}) yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

PowerDI5060-8

- DC-DC Converters
- Power Management Functions
- Analog Switch

Features and Benefits

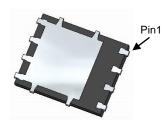
- 100% Unclamped Inductive Switch (UIS) Test in Production
- Low On-Resistance
- Fast Switching Speed
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- An Automotive-Complaint Part is Available Under Separate Datasheet (<u>DMP4011SPSQ</u>)

Mechanical Data

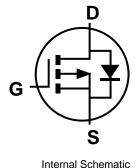
- Case: PowerDI[®] 5060-8
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish—100% Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208
- · Weight: 0.097 grams (Approximate)

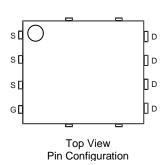


Top View



Bottom View





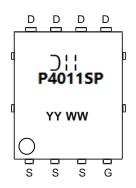
Ordering Information (Note 4)

Part Number	Case	Packaging
DMP4011SPS-13	PowerDI5060-8	2500 / Tape & Reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



);; = Manufacturer's Marking P4011SP = Product Type Marking Code YYWW = Date Code Marking YY = Year (ex: 19 = 2019) WW = Week (01 to 53)



Maximum Ratings (@ $T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage	V_{DSS}	-40	V		
Gate-Source Voltage	V _{GSS}	±20	V		
Continuous Dunin Comment (Nate 7) \	Steady	T _C = +25°C	- I _D	-76	Α
Continuous Drain Current (Note 7) V _{GS} = -10V	State	T _C = +70°C		-61	
Continuous Drain Current (Note 6)V _{GS} = -10V	Steady State	T _A = +25°C	I _D	-11.7	А
		T _A = +70°C		-9.4	
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%		I _{DM}	-300	Α	
Maximum Body Diode Continuous Current (Note 6)	Is	-8.9	Α		
Pulsed Source Current (10µs Pulse, Duty Cycle = 1	I _{SM}	-300	Α		
Avalanche Current (Note 8) L = 1mH	I _{AS}	-22	Α		
Avalanche Energy (Note 8) L = 1mH	E _{AS}	250	mJ		

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Total Power Dissipation (Note 5)	$T_A = +25^{\circ}C$	P_{D}	1.3	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	$R_{\theta JA}$	96.4	°C/W
Total Power Dissipation (Note 6)	T _A = +25°C	P _D	2.3	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	R _{0JA}	55	°C/W
Thermal Resistance, Junction to Case (Note 7)	·	R _{0JC}	1.3	°C/W
Operating and Storage Temperature Range		$T_{J_i}T_{STG}$	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 9)							
Drain-Source Breakdown Voltage	BV _{DSS}	-40	_	_	V	$V_{GS} = 0V, I_{D} = -250\mu A$	
Zero Gate Voltage Drain Current	I _{DSS}	_	_	-1	μΑ	$V_{DS} = -32V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 9)							
Gate Threshold Voltage	V _{GS(TH)}	-1.0	-2.0	-2.5	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	
Static Drain-Source On-Resistance	D		6	10	mΩ	$V_{GS} = -10V, I_D = -9.8A$	
Static Drain-Source Off-Resistance	R _{DS(ON)}	1	10	14	11177	$V_{GS} = -4.5V, I_D = -9.8A$	
Diode Forward Voltage	V_{SD}		-0.7	-1	V	$V_{GS} = 0V, I_{S} = -1A$	
DYNAMIC CHARACTERISTICS (Note 10)						_	
Input Capacitance	Ciss	1	2747	_		V 00V V 0V	
Output Capacitance	Coss	l	508		pF	$V_{DS} = -20V, V_{GS} = 0V$ f = 1MHz	
Reverse Transfer Capacitance	C _{rss}		222	_			
Gate Resistance	Rg	_	21.4		Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge (V _{GS} = -4.5V)	Q_{g}	l	25	_			
Total Gate Charge (V _{GS} = -10V)	Qg		52	_	nC	$V_{DS} = -20V$	
Gate-Source Charge	Q_{gs}		8.5	_	IIC	$I_D = -9.8A$	
Gate-Drain Charge	Q_{gd}	l	11.8	_			
Turn-On Delay Time	t _{D(ON)}		6.6	_			
Turn-On Rise Time	t _R	_	6.5	_		V_{GS} = -10V, V_{DD} = -20V, R_g = 6 Ω , I_D = -1A	
Turn-Off Delay Time	t _{D(OFF)}	_	222		ns		
Turn-Off Fall Time	t _F	ı	138	_			
Reverse Recovery Time	t _{RR}		25	_	ns	$I_F = -9.8A$, di/dt = -100A/ μ s	
Reverse Recovery Charge	Q _{RR}		17	_	nC	I _F = -9.8A, di/dt = -100A/µs	

5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

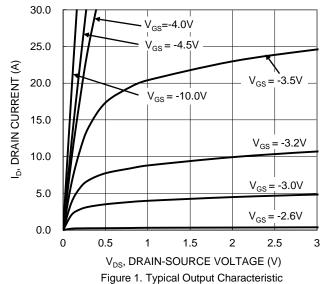
^{6.} Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.

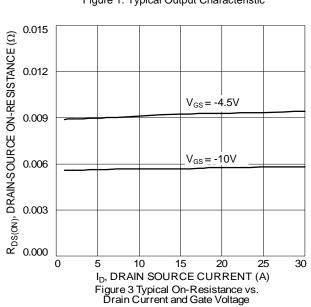
^{7.} Thermal resistance from junction to soldering point (on the exposed drain pad).

I.As and EAS ratings are based on low frequency and duty cycles to keep T_J = +25°C.
 Short duration pulse test used to minimize self-heating effect.
 Guaranteed by design. Not subject to product testing.









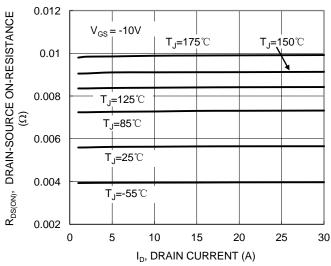
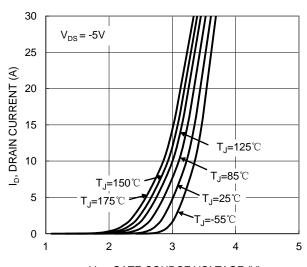


Figure 5. Typical On-Resistance vs. Drain Current and Temperature



V_{GS}, GATE-SOURCE VOLTAGE (V) Figure 2. Typical Transfer Characteristic

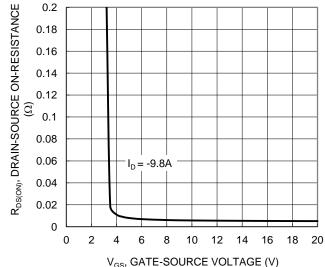


Figure 4. Typical Transfer Characteristic

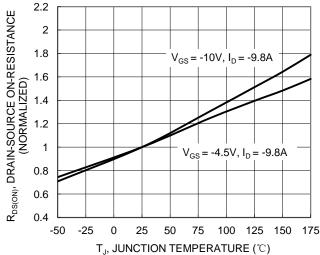


Figure 6. On-Resistance Variation with Temperature





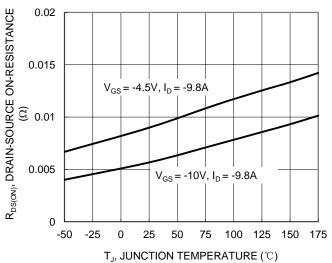
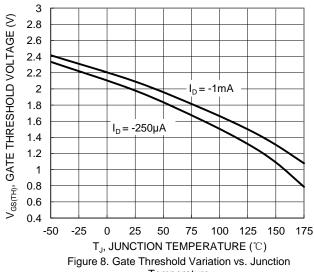


Figure 7. On-Resistance Variation with Temperature



Temperature

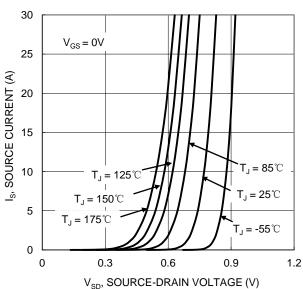


Figure 9. Diode Forward Voltage vs. Current

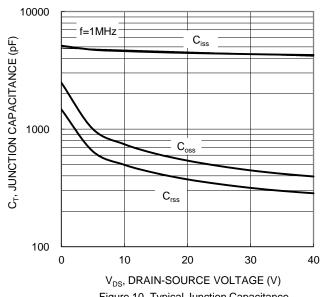


Figure 10. Typical Junction Capacitance

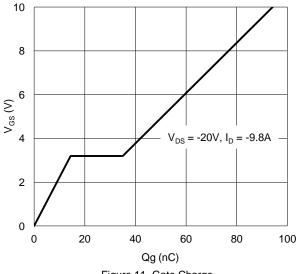


Figure 11. Gate Charge

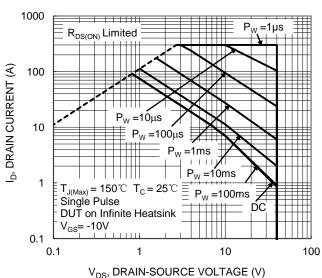


Figure 12. SOA, Safe Operation Area



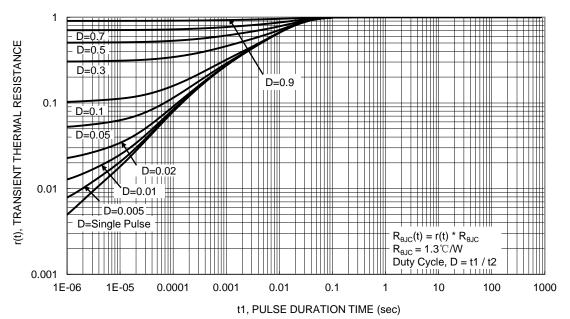


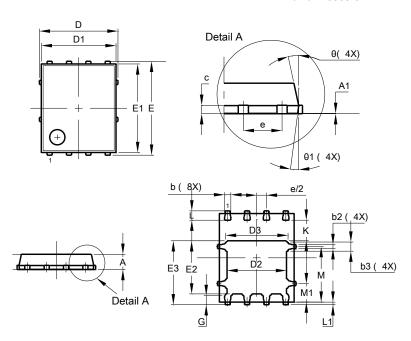
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI5060-8

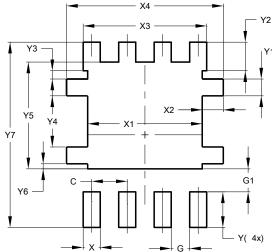


PowerDIEGED 9					
PowerDI5060-8					
Dim	Min	Max	Тур		
Α	0.90	1.10	1.00		
A1	0.00	0.05	_		
b	0.33	0.51	0.41		
b2	0.200	0.350	0.273		
b3	0.40	0.80	0.60		
С	0.230	0.330	0.277		
D		5.15 BSC	;		
D1	4.70	5.10	4.90		
D2	3.70	4.10	3.90		
D3	3.90	4.30	4.10		
E	6.15 BSC				
E1	5.60	6.00	5.80		
E2	3.28	3.68	3.48		
E3	3.99	4.39	4.19		
е	1.27 BSC				
G	0.51	0.71	0.61		
K	0.51	_	_		
L	0.51	0.71	0.61		
L1	0.100	0.200	0.175		
М	3.235	4.035	3.635		
M1	1.00	1.40	1.21		
Θ	10°	12°	11°		
Θ1	6°	8°	7°		
All	All Dimensions in mm				

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI5060-8



Dimensions	Value (in mm)			
С	1.270			
G	0.660			
G1	0.820			
X	0.610			
X1	4.100			
X2	0.755			
Х3	4.420			
X4	5.610			
Y	1.270			
Y1	0.600			
Y2	1.020			
Y3	0.295			
Y4	1.825			
Y5 3.810				
Y6	0.180			
Y7 6.610				



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